

CD74ACT175 Quadruple D-type Flip-Flop with Clear

1 Features

- Inputs are TTL-voltage compatible
- Contains four flip-flops with double-rail outputs
- Buffered inputs
- Speed of bipolar F, AS, and S, with significantly reduced power consumption
- Balanced propagation delays
- $\pm 24\text{mA}$ output drive current
 - Fanout to 15 F devices
- SCR-latchup-resistant CMOS process and circuit design

2 Applications

- Buffer/Storage Registers
- [Shift Registers](#)
- Pattern Generators

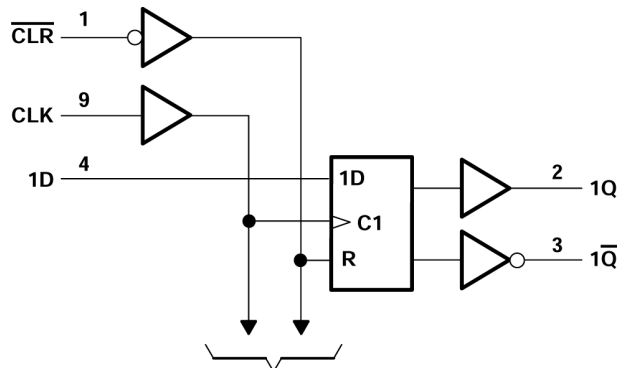
3 Description

This positive-edge-triggered D-type flip-flop has a direct clear ($\overline{\text{CLR}}$) input. The CD74ACT175 features complementary outputs from each flip-flop.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE ⁽³⁾
CD74ACT175	N (PDIP, 16)	19.3mm × 9.4mm	19.3mm × 6.35mm
	D (SOIC, 16)	9.9mm × 6mm	9.9mm × 3.9mm

- (1) For more information, see [Section 11](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.



To Three Other Channels
Logic Diagram (Positive Logic)



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4 Pin Configurations and Functions

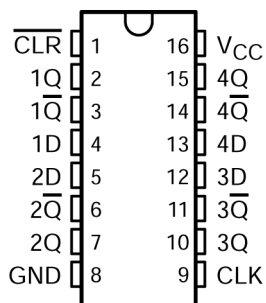


Figure 4-1. D or N Package, 16-PIN SCOIC or PDIP (Top View)

Table 4-1. Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	CLR	I	Clear Pin
2	1Q	O	1Q Output
3	1Q̄	O	1Q̄ Output
4	1D	I	1D Input
5	2D	I	2D Input
6	2Q̄	O	2Q̄ Output
7	2Q	O	2Q Output
8	GND	—	Ground Pin
9	CLK	I	Clock Input
10	3Q	O	3Q Output
11	3Q̄	O	3Q̄ Output
12	3D	I	3D Input
13	4D	I	4D Input
14	4Q̄	O	4Q̄ Output
15	4Q	O	4Q Output
16	V _{CC}	—	Power Pin

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	–0.5	6	V
I _{IK}	Input clamp current	(V _I < 0 V or V _I > V _{CC}) ⁽²⁾		±20 mA
I _{OK}	Output clamp current	(V _O < 0 V or V _O > V _{CC}) ⁽²⁾		±50 mA
I _O	Continuous output current	(V _O > 0 V or V _O < V _{CC})		±50 mA
	Continuous current through V _{CC} or GND			±200 mA
T _{stg}	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±2000 V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		2		V
V _{IL}	Low-level input voltage		0.8		0.8		0.8	V
V _I	Input voltage	0	V _{CC}	0	V _{CC}	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		–24		–24		–24	mA
I _{OL}	Low-level output current		24		24		24	mA
Δt/Δv	Input transition rise or fall rate		10		10		10	ns/V

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

5.4 Thermal Information

THERMAL METRIC		N (PDIP)	D (SOIC)	UNIT
		16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	67	106.6	°C/W

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25 °C		–55°C to 125°C		–40°C to 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = –50 µA	4.5 V	4.4		4.4		4.4		V
		I _{OH} = –24 mA	4.5 V	3.94		3.7		3.8		
		I _{OH} = –50 mA ⁽¹⁾	5.5 V			3.85				
		I _{OH} = –75 mA ⁽¹⁾	5.5 V					3.85		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 50 µA	4.5 V		0.1		0.1		0.1	V
		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	
		I _{OL} = 50 mA ⁽¹⁾	5.5 V				1.65			
		I _{OL} = 75 mA ⁽¹⁾	5.5 V						1.65	
I _I	V _I = V _{CC} or GND		5.5 V		±0.1		±1		±1	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0		5.5 V		8		160		80	µA
ΔI _{CC} ⁽²⁾	V _I = V _{CC} – 2.1 V		4.5 V to 5.5 V		2.4		3		2.8	mA
C _i					10		10		10	pF

- (1) Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.
- (2) Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

Table 5-1. Act Input Load Table

INPUT	UNIT LOAD
Data	0.58
CLR	0.67
CLK	0.92

5.6 Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted)

			–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency			144		114	MHz
t _w	Pulse duration	CLR low	4		3.5		ns
		CLK high or low	5		4.4		
t _{su}	Setup time before CLK↑	Data	2		2		ns
t _h	Hold time, data after CLK ↑		2		2		ns
t _{rec}	Recovery time, before CLK ↑	CLR↑	1		1		ns

5.7 Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$, $C_L = 50\text{ pF}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
f_{\max}			114		114		MHz
t_{PLH}	CLK	Any Q	2.9	11.5	3	10.5	ns
t_{PHL}			2.9	11.5	3	10.5	
t_{PLH}	$\overline{\text{CLR}}$	Any Q	3.3	13	3.3	11.8	ns
t_{PHL}			3.3	13	3.3	11.8	

5.8 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TYP	UNIT
C_{pd}	Power dissipation capacitance	55	pF

6 Parameter Measurement Information

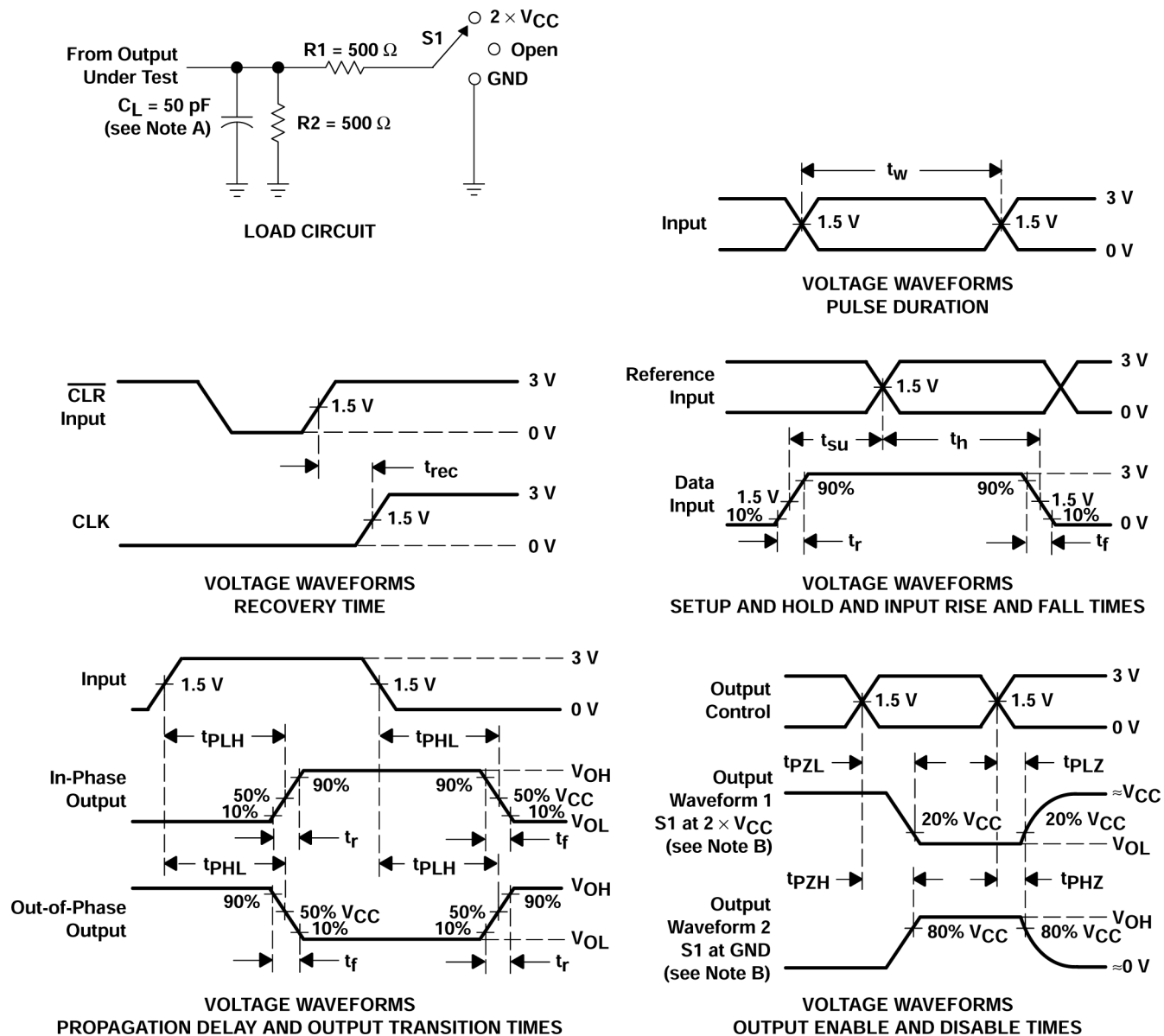


Figure 6-1. Load Circuit and Voltage Waveforms

- A. C_L includes probe and test-fixture capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 3$ ns, $t_f = 3$ ns. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. t_{PLH} and t_{PHL} are the same as t_{pd} .
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- I. All parameters and waveforms are not applicable to all devices.

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

7 Detailed Description

7.1 Overview

Information at the data (D) inputs meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going edge of CLK. When CLK is at either the high or low level, the D input has no effect at the output.

7.2 Functional Block Diagram

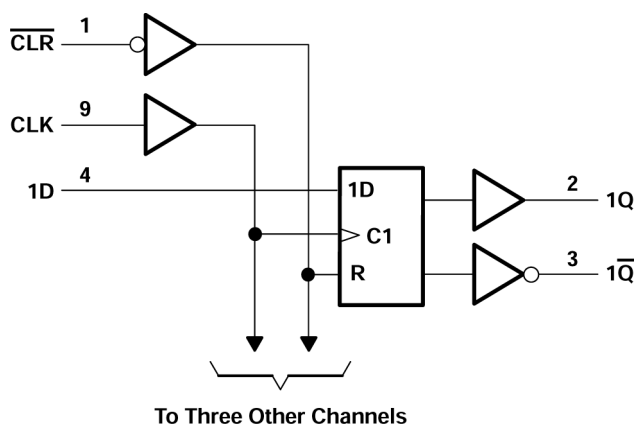


Figure 7-1. Logic Diagram (Positive Logic)

7.3 Device Functional Modes

Table 7-1. Function Table (Each Flip-flop)

INPUTS			OUTPUT	
CLR	CLK	D	Q	\bar{Q}
L	X	X	L	H
H	\uparrow	H	H	L
H	\uparrow	L	L	H
H	L	X	Q_0	\bar{Q}_0

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Power Supply Recommendations

The power supply can be any voltage between the min and max supply voltage rating located in [Section 5.3](#).

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends 0.1 μF and if there are multiple V_{CC} terminals, then TI recommends .01 μF or .022 μF for each power terminal. It is okay to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1 μF and 1 μF are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

8.2 Layout

8.2.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. It is generally okay to float outputs unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This does not disable the input section of the IOs so they cannot float when disabled.

9 Device and Documentation Support

9.1 Documentation Support (Analog)

9.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 9-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
CD54ACT175	Click here	Click here	Click here	Click here	Click here
CD74ACT175	Click here	Click here	Click here	Click here	Click here

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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9.4 Trademarks

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9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (April 2003) to Revision A (May 2024)	Page
• Added <i>Applications</i> section, <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Updated thermal values for RθJA: D = 73 to 106.6, all values in °C/W	4

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD74ACT175E	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74ACT175E
CD74ACT175E.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74ACT175E
CD74ACT175EE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74ACT175E
CD74ACT175M	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-55 to 125	ACT175M
CD74ACT175M96	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT175M
CD74ACT175M96.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT175M

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT175M96	SOIC	D	16	2500	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1
CD74ACT175M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT175M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT175M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74ACT175M96	SOIC	D	16	2500	353.0	353.0	32.0
CD74ACT175M96	SOIC	D	16	2500	353.0	353.0	32.0

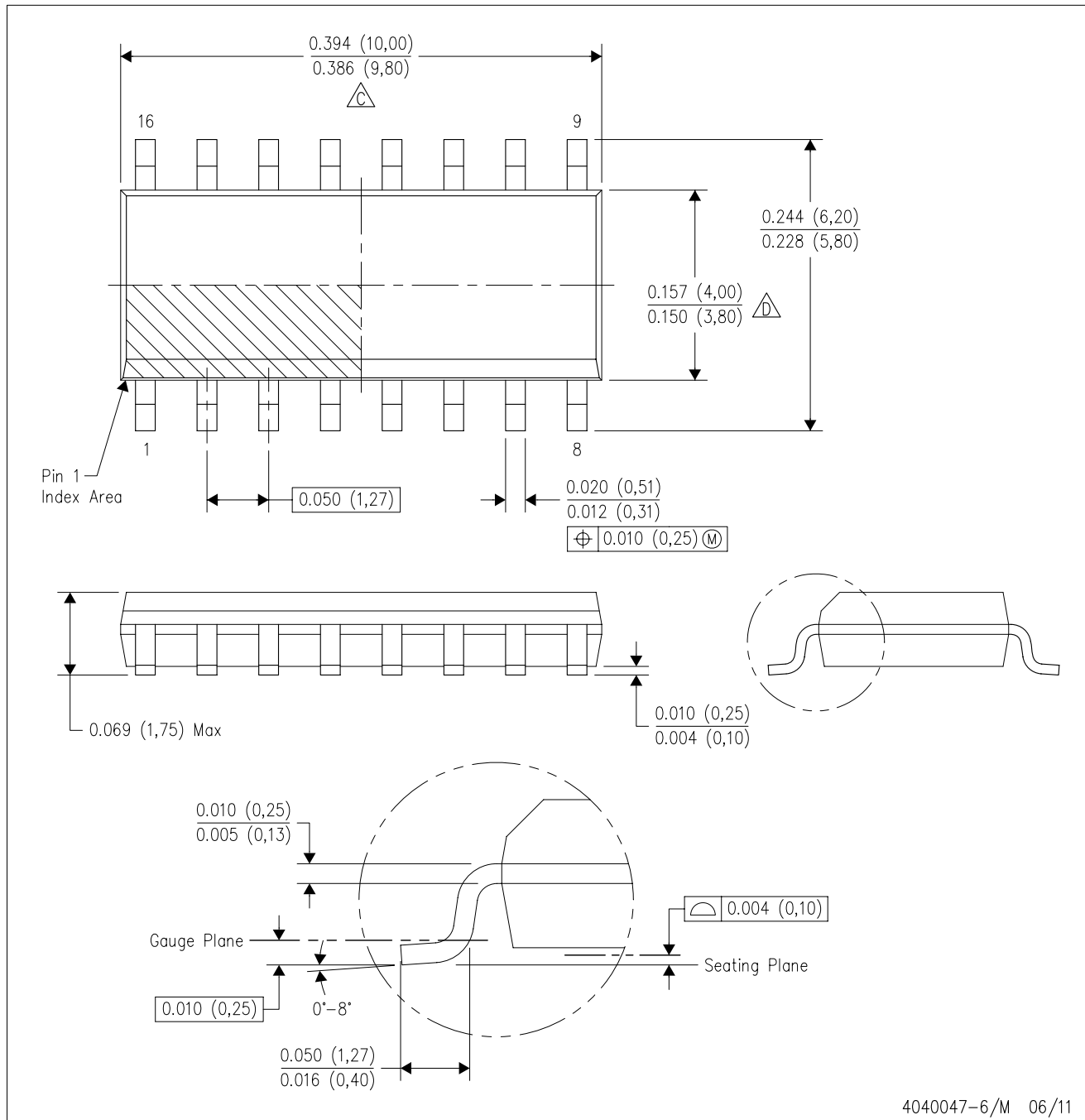
TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74ACT175E	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT175E	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT175E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT175E.A	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT175EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT175EE4	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

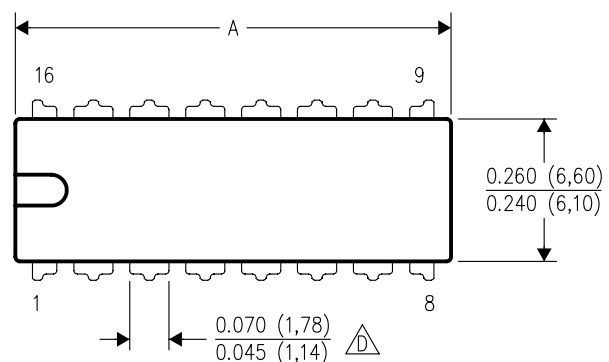


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

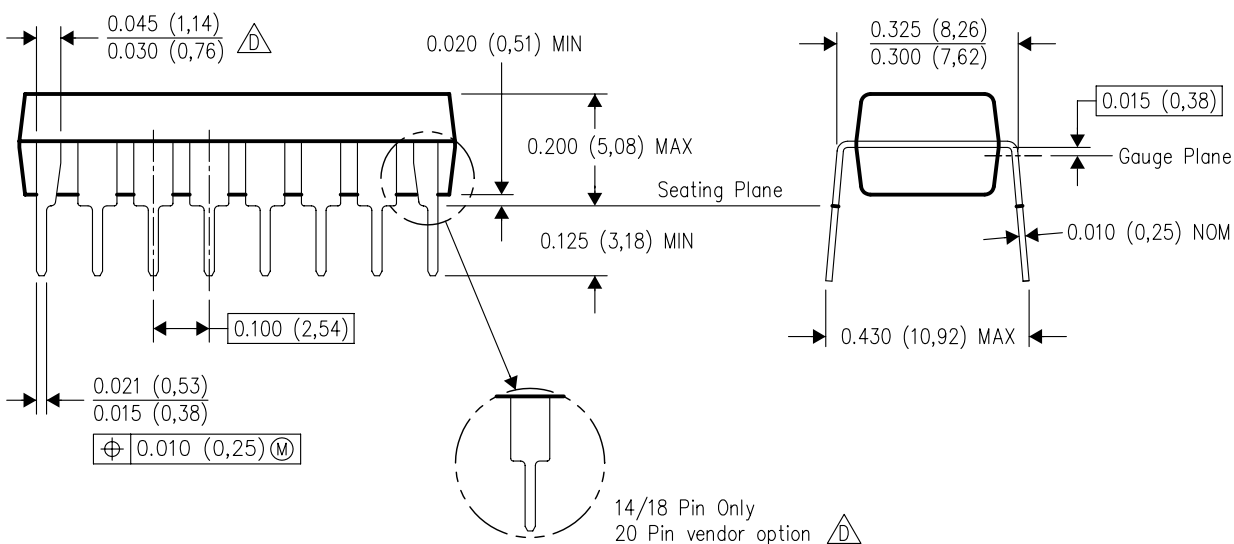
N (R-PDIP-T**)

16 PINS SHOWN



PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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